FICHA TÉCNICA

LOCTITE® SI 5920™

WelderPower®
Premium Welding Products.

PRODUCT DESCRIPTION
LOCTITE® SI 5920™ provides the following product characteristics:

Technology	Silicone
Chemical Type	Silicone
Appearance (uncured)	Copper colored paste
Components	One component – requires no mixing
Thixotropic	Reduced migration of liquid product after application to substrate.
Cure	Room temperature vulcanizing (RTV)
Application	Gasketing and sealing
Specific benefits	Adheres to a wide range of substrates

LOCTITE® SI 5920™ is a moisture-curing, non-corrosive silicone. The thixotropic nature of LOCTITE® SI 5920™ reduces the migration of liquid product after application to the substrate. It has been designed specially for gasketing and sealing applications where excellent temperature resistance is required. It is also used for electrical insulating applications. This product is typically used in applications up to 350°C.

Typical properties of uncured material

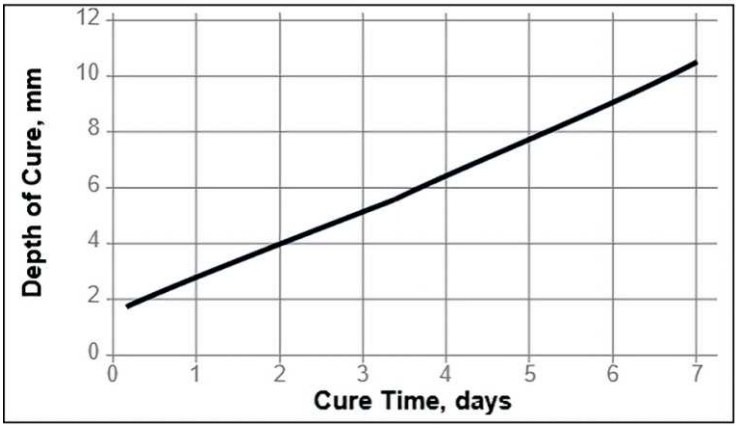
Specific Gravity @ 22°C	1.05
Flash point - see SDS	
Extrusion Rate, g/min:	
Pressure 0.62 MPa, time 15 seconds, temperature 22°C: Semco cartridge	≥275
Flow, ISO 7390, mm:	
After 2 minutes	≤13

Typical curing performance

Surface cure
Tack free time is the time required to achieve a tack free surface.

Tack free time, minutes	
Cured @ 22 °C / 50±5 % RH	20 to 60
Skin over time, minutes	20

Depth of cure
The graph below shows the increase in depth of cure with time at @ 22°C.



Typical properties of cured material
Cured for 7 days @ 25 °C, 50±5% RH

Physical properties:		
Shore Hardness, ISO 868, Durometer A		23 to 38
Elongation, ISO 37, %		≥350
Tensile Strength, ISO 37	N/mm^2 (psi)	≥1.4 (205)

Cured for 21 days @ 22 °C, 50±5% RH

Physical properties:	
Coefficient of thermal expansion, ISO 11359-2, K^{-1}:	340×10^{-6}
Electrical properties:	
Volume resistivity, IEC 60093, Ω·cm	5.5×10^{15}
Surface resistivity, IEC 60093, Ω·cm	200×10^{15}

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